



Microtips

TECHNOLOGY

EPD Module User Manual

MT-DEPG0270BNS760F0

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Specification for 2.7 inch EPD

Model NO. : MT-DEPG0270BNS760F0

MT's Confirmation:

Prepared by	Checked by	Approved by

Customer approval:

Customer	Approved by	Date

Revision History

Version	Content	Date	Producer
1.0	New release	2019/2/21	
1.1	1、Updata Typical Application Circuit with SPI Interface 2、Updata the module partial parameter 3、Updata Packaging	2019/08/20	

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1. Over View

MT-DEPG0270BNS760F0 is an Active Matrix Electrophoretic Display (AM EPD), with interface and a reference system design. The display is capable to display image at 1-bit white, black full display capabilities. The 2.7inch active area contains 264×176pixels. The module is a TFT-array driving electrophoresis display, with integrated circuits including gate driver, source driver, MCU interface, timing controller, oscillator, DC-DC, SRAM, LUT, VCOM. Module can be used in portable electronic devices, such as Electronic Shelf Label (ESL) System.

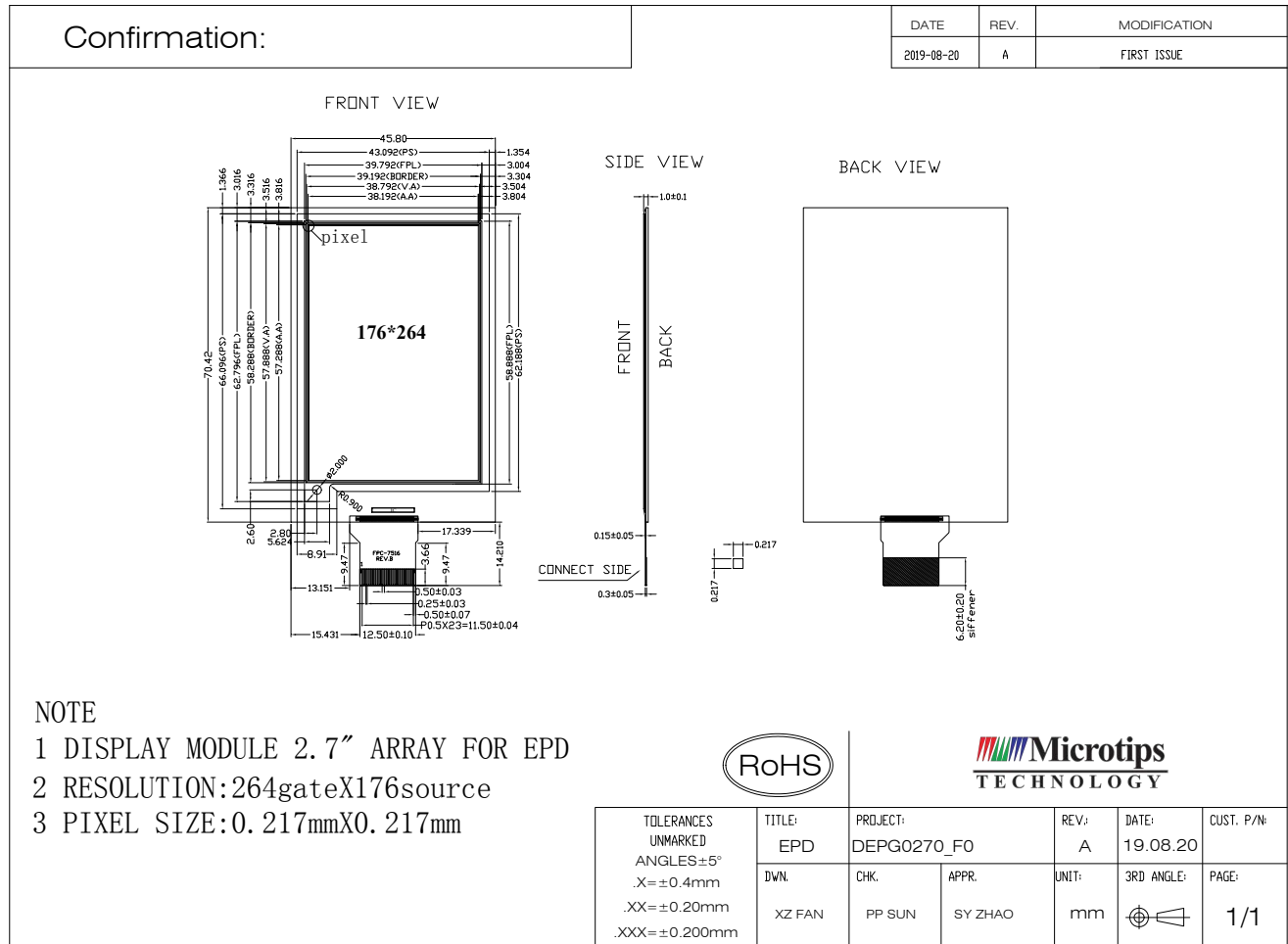
2. Features

- ◆ 264×176 pixels display
- ◆ High contrast High reflectance
- ◆ Ultra wide viewing angle Ultra low power consumption
- ◆ Pure reflective mode
- ◆ Bi-stable display
- ◆ Commercial temperature range
- ◆ Landscape portrait modes
- ◆ Hard-coat antiglare display surface
- ◆ Ultra Low current deep sleep mode
- ◆ On chip display RAM
- ◆ Waveform can stored in On-chip OTP or written by MCU
- ◆ Serial peripheral interface available
- ◆ On-chip oscillator
- ◆ On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- ◆ I²C signal master interface to read external temperature sensor
- ◆ Built-in temperature sensor

3. Mechanical Specification

Parameter	Specifications	Unit	Remark
Screen Size	2.7	Inch	
Display Resolution	264(H)×176(V)	Pixel	DPI:117
Active Area	38.192×57.288	mm	
Pixel Pitch	0.217×0.217	mm	
Pixel Configuration	Rectangle		
Outline Dimension	45.8 (H)×70.42(V) ×1.00(D)	mm	
Weight	5.5±0.5	g	

4. Mechanical Drawing of EPD Module



5. Input/output Pin Assignment

No.	Name	I/O	Description	Remark
1	NC		Do not connect with other NC pins	Keep Open
2	GDR	O	N-Channel MOSFET Gate Drive Control	
3	RESE	I	Current Sense Input for the Control Loop	
4	NC	NC	Do not connect with other NC pins	Keep Open
5	VSH2	C	Positive Source driving voltage	
6	TSCL	O	I2C Interface to digital temperature sensor Clock pin	
7	TSDA	I/O	I2C Interface to digital temperature sensor Data pin	
8	BS1	I	Bus Interface selection pin	Note 5-5
9	BUSY	O	Busy state output pin	Note 5-4
10	RES#	I	Reset signal input. Active Low.	Note 5-3
11	D/C#	I	Data /Command control pin	Note 5-2
12	CS#	I	Chip select input pin	Note 5-1
13	SCL	I	Serial Clock pin (SPI)	
14	SDA	I	Serial Data pin (SPI)	
15	VDDIO	P	Power Supply for interface logic pins It should be connected with VCI	
16	VCI	P	Power Supply for the chip	
17	VSS	P	Ground	
18	VDD	C	Core logic power pin VDD can be regulated internally from VCI. A capacitor should be connected between VDD and VSS	
19	VPP	P	FOR TEST	Keep Open
20	VSH1	C	Positive Source driving voltage	
21	VGH	C	Power Supply pin for Positive Gate driving voltage and VSH1	
22	VSL	C	Negative Source driving voltage	
23	VGL	C	Power Supply pin for Negative Gate driving voltage VCOM and VSL	
24	VCOM	C	VCOM driving voltage	

I = Input Pin, O =Output Pin, /O = Bi-directional Pin (Input/output), P = Power Pin, C = Capacitor Pin

Note 5-1: This pin (CS#) is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW.

Note 5-2: This pin is (D/C#) Data/Command control pin connecting to the MCU in 4-wire SPI mode. When the pin is pulled HIGH, the data at SDA will be interpreted as data. When the pin is pulled LOW, the data at SDA will be interpreted as command.

Note 5-3: This pin (RES#) is reset signal input. The Reset is active low.

Note 5-4: This pin is Busy state output pin. When Busy is High, the operation of chip should not be interrupted, command should not be sent. The chip would put Busy pin High when -Outputting display waveform -Communicating with digital temperature sensor

Note 5-5: Bus interface selection pin

BS1 State	MCU Interface
L	4-lines serial peripheral interface(SPI) - 8 bits SPI
H	3- lines serial peripheral interface(SPI) - 9 bits SPI

6. Electrical Characteristics

6.1 Absolute Maximum Rating

Parameter	Symbol	Rating	Unit
Logic supply voltage	VCI	-0.5 to +4.0	V
Logic Input voltage	VIN	-0.5 to VCI +0.5	V
Logic Output voltage	VOUT	-0.5 to VCI +0.5	V
Operating Temp range	TOPR	0 to +50	°C.
Storage Temp range	TSTG	-25 to+70	°C.
Optimal Storage Temp	TSTGo	23±2	°C.
Optimal Storage Humidity	HSTGo	55±10	%RH

Note:

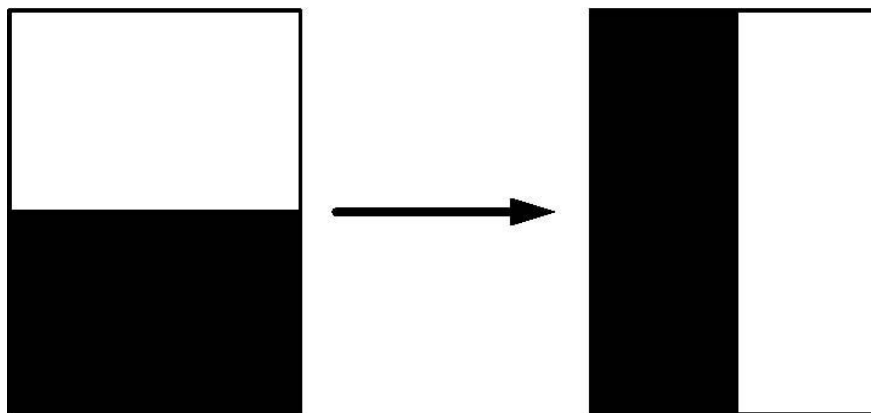
1.Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Panel DC Characteristics tables.

6.2 Panel DC Characteristics

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =25°C.

Parameter	Symbol	Condition	Applicable pin	Min.	Typ.	Max.	Unit
Single ground	V _{SS}	-		-	0	-	V
Logic supply voltage	V _{CI}	-	V _{CI}	2.2	3.0	3.7	V
Core logic voltage	V _{DD}		V _{DD}	1.7	1.8	1.9	V
High level input voltage	V _{IH}	-	-	0.8 V _{CI}	-	-	V
Low level input voltage	V _{IL}	-	-	-	-	0.2 V _{CI}	V
High level output voltage	V _{OH}	I _{OH} = -100uA	-	0.9 V _{CI}	-	-	V
Low level output voltage	V _{OL}	I _{OL} = 100uA	-	-	-	0.1 V _{CI}	V
Typical power	P _{TYP}	V _{CI} =3.0V	-	-	9	-	mW
Deep sleep mode	P _{STPY}	V _{CI} =3.0V	-	-	0.003	-	mW
Typical operating current	I _{opr_VCI}	V _{CI} =3.0V	-	-	3	-	mA
Image update time	-	23 °C	-	-	3	-	sec
Sleep mode current	I _{slp_VCI}	DC/DC off No clock No input load Ram data retain	-	-	20	-	uA
Deep sleep mode current	I _{dslp_VCI}	DC/DC off No clock No input load Ram data not retain	-	-	1	5	uA

Notes: 1. The typical power is measured with following transition from horizontal 2 scale pattern to vertical 2 scale pattern.



2. The deep sleep power is the consumed power when the panel controller is in deep sleep mode.

3. The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by MT.

6.3 Panel DC Characteristics(Driver IC Internal Regulators)

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =25°C.

Parameter	Symbol	Condition	Applicable pin	Min.	Typ.	Max.	Unit
VCOM output voltage	VCOM	-	VCOM	-	TBD	-	V
Positive Source output voltage	V _{SH}	-	S ₀ ~S ₁₂₇	+14.5	+15	+15.5	V
Negative Source output voltage	V _{SL}	-	S ₀ ~S ₁₂₇	-15.5	-15	-14.5	V
Positive gate output voltage	V _{gh}	-	G ₀ ~G ₂₉₅	+21	+22	+23	V
Negative gate output voltage	V _{gl}	-	G ₀ ~G ₂₉₅	-21	-20	-19	V

6.4 Panel AC Characteristics

6.4.1 MCU Interface Selection

The pin assignment at different interface mode is summarized in Table 6-4-1. Different MCU mode can be set by hardware selection on BS1 pins. The display panel only supports 4-wire SPI or 3-wire SPI interface mode.

Pin Name	Data/Command Interface		Control Signal		
	SDA	SCL	CS#	D/C#	RES#
Bus interface	SDA	SCL	CS#	D/C#	RES#
BS1=L 4-wire SPI	SDA	SCL	CS#	D/C#	RES#
BS1=H 3-wire SPI	SDA	SCL	CS#	L	RES#

6.4.2 MCU Serial Interface (4-wire SPI)

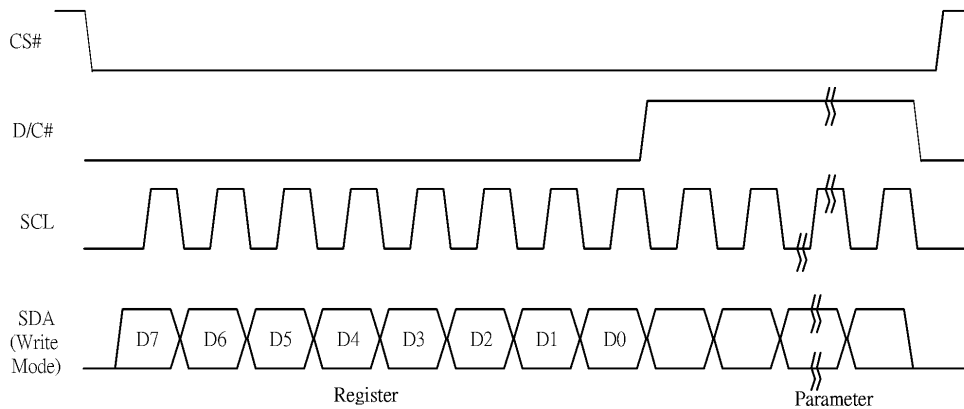
The serial interface consists of serial clock SCL, serial data SDA, D/C#, CS#. This interface supports Write mode and Read mode.

Function	CS#	D/C#	SCL
Write command	L	L	↑
Write data	L	H	↑

Note: ↑ stands for rising edge of signal

In the write mode SDA is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0. The level of D/C# should be kept over the whole byte. The data byte in the shift register is written to the Graphic Display Data RAM /Data Byte register or command Byte register according to D/C# pin.

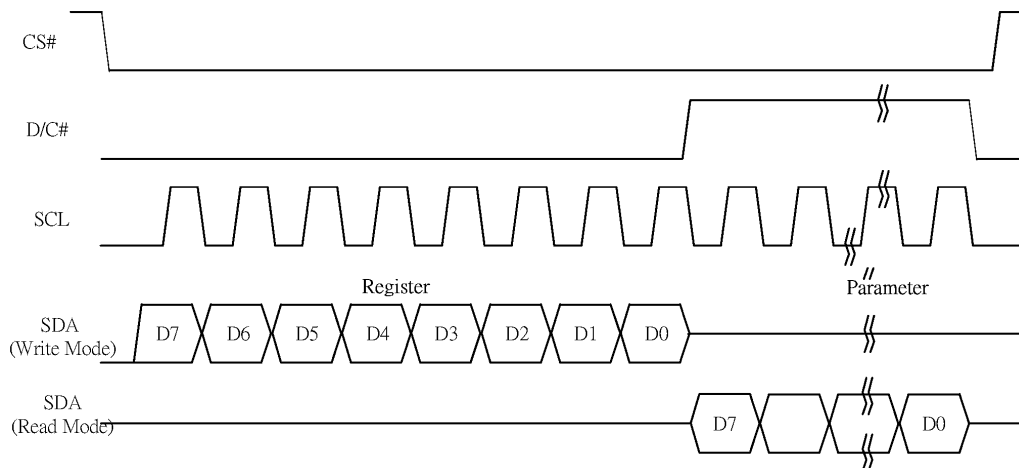
Figure 6-1: Write procedure in 4-wire SPI mode



In the Read mode:

1. After driving CS# to low, MCU need to define the register to be read.
2. SDA is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0 with D/C# keep low.
3. After SCL change to low for the last bit of register, D/C# need to drive to high.
4. SDA is shifted out an 8-bit data on every falling edge of SCL in the order of D7, D6, ... D0.
5. Depending on register type, more than 1 byte can be read out. After all byte are read, CS# need to drive to high to stop the read operation.

Figure 6-2: Read procedure in 4-wire SPI mode



6.4.3 MCU Serial Interface (3-wire SPI)

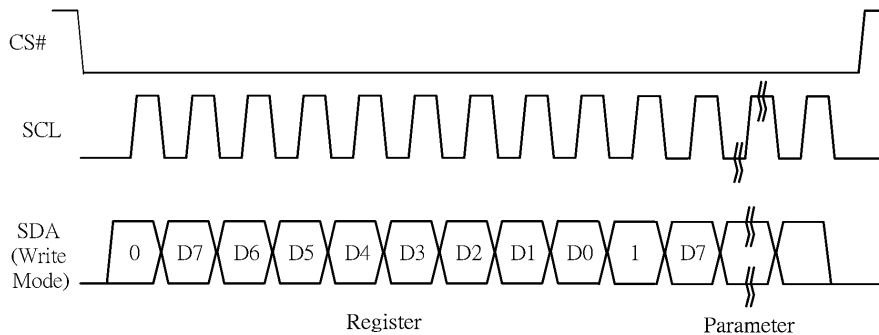
The 3-wire serial interface consists of serial clock SCL, serial data SDA and CS#. This interface also supports Write mode and Read mode.

The operation is similar to 4-wire serial interface while D/C# pin is not used. There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence: D/C# bit, D7 to D0 bit. The D/C# bit (first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0).

Function	CS#	D/C#	SCL
Write command	L	Tie	↑
Write data	L	Tie	↑

Note: ↑ stands for rising edge of signal

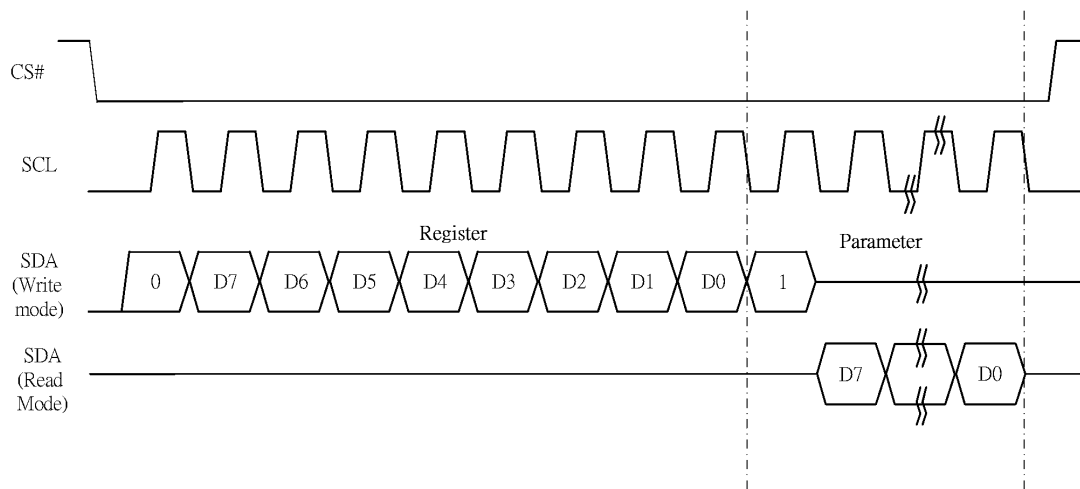
Figure 6-3: Write procedure in 3-wire SPI mode



In the Read mode:

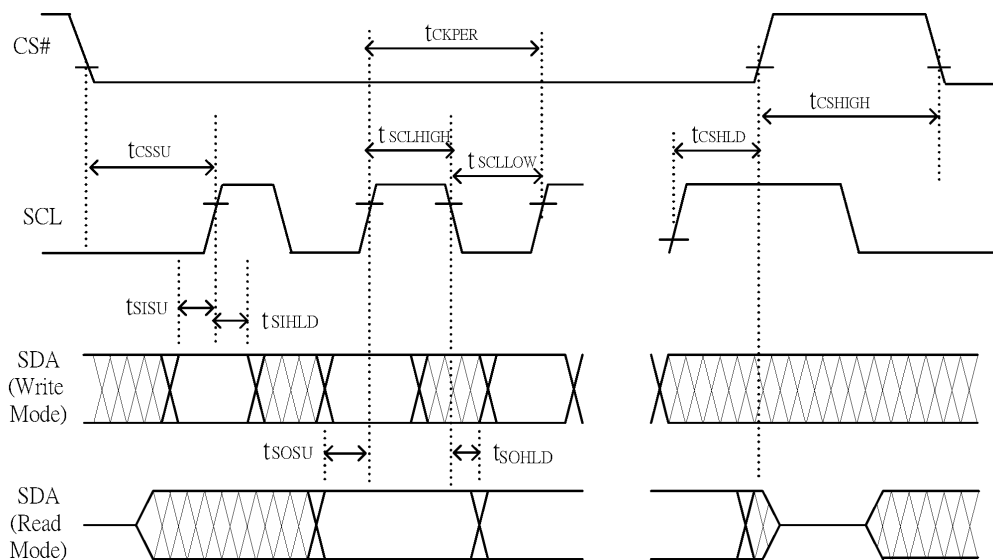
1. After driving CS# to low, MCU need to define the register to be read.
2. D/C=0 is shifted thru SDA with one rising edge of SCL
3. SDA is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0.
4. D/C=1 is shifted thru SDA with one rising edge of SCL
5. SDA is shifted out an 8-bit data on every falling edge of SCL in the order of D7, D6, ... D0.
6. Depending on register type, more than 1 byte can be read out. After all byte are read, CS# need to drive to high to stop the read operation.

Figure 6-4: Read procedure in 3-wire SPI mode



6.4.4 Interface Timing

The following specifications apply for: VSS=0V, VCI=3.0V, T_{OPR} =23°C.



Changed Diagram

Serial Interface Timing Characteristics

(VCI - VSS = 2.2V to 3.7V, TOPR = 25°C, CL=20pF)

Write mode

Symbol	Parameter	Min	Typ.	Max	Unit
fSCL	SCL frequency (Write Mode)			20	MHz
tCSSU	Time CS# has to be low before the first rising edge of SCLK	20			ns
tCSHLD	Time CS# has to remain low after the last falling edge of SCLK	20			ns
tCSHIGH	Time CS# has to remain high between two transfers	100			ns
tSCLHIGH	Part of the clock period where SCL has to remain high	25			ns
tSCLLOW	Part of the clock period where SCL has to remain low	25			ns
tSISU	Time SI (SDA Write Mode) has to be stable before the next rising edge of SCL	10			ns
tSIHLD	Time SI (SDA Write Mode) has to remain stable after the rising edge of SCL	40			ns

Read mode

Symbol	Parameter	Min	Typ.	Max	Unit
fSCL	SCL frequency (Read Mode)			2.5	MHz
tCSSU	Time CS# has to be low before the first rising edge of SCLK	100			ns
tCSHLD	Time CS# has to remain low after the last falling edge of SCLK	50			ns
tCSHIGH	Time CS# has to remain high between two transfers	250			ns
tSCLHIGH	Part of the clock period where SCL has to remain high	180			ns
tSCLLOW	Part of the clock period where SCL has to remain low	180			ns
tSOSU	Time SO(SDA Read Mode) will be stable before the next rising edge of SCL		50		ns
tSOHLD	Time SO (SDA Read Mode) will remain stable after the falling edge of SCL		0		ns

7.Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description				
0	0	01	0	0	0	0	0	0	0	1	Driver Output control	Gate setting Set A[8:0]=127h[POR] Set B[2:0]=000h[POR]				
0	1		A ₇	A ₆	A ₅	A ₄	A ³	A ₂	A ₁	A ₀						
0	1		0	0	0	0	0	0	0	A ₈						
0	1		0	0	0	0	0	B ₂	B ₁	B ₀						
0	0	03	0	0	0	0	0	0	1	1	Gate Driving voltage control	Set Gate Driving voltage A[4:0]=00h[POR] VGH setting from 12V to 20V				
0	1		0	0	0	A ₄	A ₃	A ₂	A ₁	A ₀						
													A[4:0]	VGH	A[4:0]	VGH
													07h	12	10h	16.5
													08h	12.5	11h	17
													09h	13	12h	17.5
													0Ah	13.5	13h	18
													0Bh	14	14h	18.5
													0Ch	14.5	15h	19
													0Dh	15	16h	19.5
											0Eh	15.5	17h	20		
											0Fh	16	Other	NA		
0	0	04	0	0	0	0	0	1	0	0	Source Driving voltage control	Set Source Driving voltage A[7:0]= 41h[POR], VSH1 at 15V B[7:0]=A8h[POR], VSH2 at 5 V C[7:0]= 32h[POR], VSL at -15V				
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀						
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀						
0	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀						

A[7]/B[7] = 1,
VSH1/VSH2 voltage setting from 2.4V to 8.8V

A/B[7:0]	VSH1/VSH2	A/B[7:0]	VSH1/VSH2
8Eh	2.4	AFh	5.7
8Fh	2.5	B0h	5.8
90h	2.6	B1h	5.9
91h	2.7	B2h	6
92h	2.8	B3h	6.1
93h	2.9	B4h	6.2
94h	3	B5h	6.3
95h	3.1	B6h	6.4
96h	3.2	B7h	6.5
97h	3.3	B8h	6.6
98h	3.4	B9h	6.7
99h	3.5	BAh	6.8
9Ah	3.6	BBh	6.9
9Bh	3.7	BCh	7
9Ch	3.8	BDh	7.1
9Dh	3.9	BEh	7.2
9Eh	4	BFh	7.3
9Fh	4.1	C0h	7.4
A0h	4.2	C1h	7.5
A1h	4.3	C2h	7.6
A2h	4.4	C3h	7.7
A3h	4.5	C4h	7.8
A4h	4.6	C5h	7.9
A5h	4.7	C6h	8
A6h	4.8	C7h	8.1
A7h	4.9	C8h	8.2
A8h	5	C9h	8.3
A9h	5.1	CAh	8.4
AAh	5.2	CBh	8.5
ABh	5.3	CCh	8.6
ACH	5.4	CDh	8.7
ADh	5.5	CEh	8.8
A Eh	5.6	Other	NA

A[7]/B[7] = 0,
VSH1/VSH2 voltage setting from 9V to 17V

A/B[7:0]	VSH1/VSH2	A/B[7:0]	VSH1/VSH2
23h	9	3Ch	14
24h	9.2	3Dh	14.2
25h	9.4	3Eh	14.4
26h	9.6	3Fh	14.6
27h	9.8	40h	14.8
28h	10	41h	15
29h	10.2	42h	15.2
2Ah	10.4	43h	15.4
2Bh	10.6	44h	15.6
2Ch	10.8	45h	15.8
2Dh	11	46h	16
2Eh	11.2	47h	16.2
2Fh	11.4	48h	16.4
30h	11.6	49h	16.6
31h	11.8	4Ah	16.8
32h	12	4Bh	17
33h	12.2	Other	NA
34h	12.4		
35h	12.6		
36h	12.8		
37h	13		
38h	13.2		
39h	13.4		
3Ah	13.6		
3Bh	13.8		

C[7] = 0,
VSL setting from -9V to -17V

C[7:0]	VSL
1Ah	-9
1Ch	-9.5
1Eh	-10
20h	-10.5
22h	-11
24h	-11.5
26h	-12
28h	-12.5
2Ah	-13
2Ch	-13.5
2Eh	-14
30h	-14.5
32h	-15
34h	-15.5
36h	-16
38h	-16.5
3Ah	-17
Other	NA

0	0	10	0	0	0	1	0	0	0	0	0	Deep Sleep mode	Deep Sleep mode Control: <table border="1"> <thead> <tr> <th>A[1:0]</th> <th>Description</th> </tr> </thead> <tbody> <tr><td>00</td><td>Normal Mode [POR]</td></tr> <tr><td>01</td><td>Enter Deep Sleep Mode1</td></tr> <tr><td>11</td><td>Enter Deep Sleep Mode2</td></tr> </tbody> </table> <p>After this command initiated, the chip will enter Deep Sleep Mode, BUSY pad will keep output high. Remark: To Exit Deep Sleep mode, User required to send HWRESET to the driver.</p>	A[1:0]	Description	00	Normal Mode [POR]	01	Enter Deep Sleep Mode1	11	Enter Deep Sleep Mode2
A[1:0]	Description																				
00	Normal Mode [POR]																				
01	Enter Deep Sleep Mode1																				
11	Enter Deep Sleep Mode2																				
0	0	11	0	0	0	1	0	0	0	1	1	Data Entry mode setting	Define data entry sequence A[2:0] = 011 [POR] A [1:0] = ID[1:0] Address automatic increment / decrement setting The setting of incrementing or								
0	1		0	0	0	0	0	A ₂	A ₁	A ₀											

0	0	12	0	0	0	1	0	0	1	0	SW RESET	It resets the commands and parameters to their S/W Reset default values except R10h-Deep Sleep Mode During operation, BUSY pad will output high. Note: RAM are unaffected by this command.												
0	0	18	0	0	0	1	1	0	0	0	Temperature Sensor Control	Temperature Sensor Selection A[7:0] = 48h [POR], external temperature sensor A[7:0] = 80h Internal temperature sensor												
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀														
0	0	1A	0	0	0	1	1	0	1	0	Temperature Sensor Control (Write to temperature register)	Write to temperature register. A[11:0]= 7FFh [POR]												
0	1		A ₁₁	A ₁₀	A ₉	A ₈	A ₇	A ₆	A ₅	A ₄														
0	1		A ₃	A ₂	A ₁	A ₀	0	0	0	0														
0	0	20	0	0	1	0	0	0	0	0	Master Activation	Activate Display Update Sequence The Display Update Sequence Option is located at R22h. BUSY pad will output high during operation. User should not interrupt this operation to avoid corruption of panel images.												
0	0	21	0	0	1	0	0	0	0	1	Display Update Control 1	RAM content option for Display Update A[7:0] = 00h [POR] A[7:4] Red RAM option <table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td>0000</td><td>Normal</td></tr> <tr><td>0100</td><td>Bypass RAM content as 0</td></tr> <tr><td>1000</td><td>Inverse RAM content</td></tr> </table> A[3:0] BW RAM option <table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td>0000</td><td>Normal</td></tr> <tr><td>0100</td><td>Bypass RAM content as 0</td></tr> <tr><td>1000</td><td>Inverse RAM content</td></tr> </table>	0000	Normal	0100	Bypass RAM content as 0	1000	Inverse RAM content	0000	Normal	0100	Bypass RAM content as 0	1000	Inverse RAM content
0000	Normal																							
0100	Bypass RAM content as 0																							
1000	Inverse RAM content																							
0000	Normal																							
0100	Bypass RAM content as 0																							
1000	Inverse RAM content																							
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀														
0	0	22	0	0	1	0	0	0	1	0	Display Update Control 2	Display Update Sequence Option: Enable the stage for Master Activation A[7:0]= FFh (POR)												
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀														

0	0	24	0	0	1	0	0	1	0	0	Write RAM (BW)	<p>After this command, data entries will be written into the 1RAM until another command is written. Address pointers will advance accordingly.</p> <p>For Write pixel: Content of write RAM(BW)=1 For Black pixel: Content of write RAM(BW)=0</p>																																																																
0	0	26	0	0	1	0	0	1	1	0	Write RAM (RED)	<p>After this command, data entries will be written into the RED RAM until another command is written. Address pointers will advance accordingly.</p> <p>For RED pixel: Content of write RAM(RED)=1 For White/Black pixel: Content of write RAM(RED)=0</p>																																																																
0	0	2C	0	0	1	0	1	1	0	0	Write VCOM register	<p>Write VCOM register from MCU interface A[7:0]=00h [POR]</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th>A[7:0]</th> <th>VOCM</th> <th>A[7:0]</th> <th>VOCM</th> </tr> </thead> <tbody> <tr><td>08h</td><td>-0.2</td><td>44h</td><td>-1.7</td></tr> <tr><td>0Ch</td><td>-0.3</td><td>48h</td><td>-1.8</td></tr> <tr><td>10h</td><td>-0.4</td><td>4Ch</td><td>-1.9</td></tr> <tr><td>14h</td><td>-0.5</td><td>50h</td><td>-2</td></tr> <tr><td>18h</td><td>-0.6</td><td>54h</td><td>-2.1</td></tr> <tr><td>1Ch</td><td>-0.7</td><td>58h</td><td>-2.2</td></tr> <tr><td>20h</td><td>-0.8</td><td>5Ch</td><td>-2.3</td></tr> <tr><td>24h</td><td>-0.9</td><td>60h</td><td>-2.4</td></tr> <tr><td>28h</td><td>-1</td><td>64h</td><td>-2.5</td></tr> <tr><td>2Ch</td><td>-1.1</td><td>68h</td><td>-2.6</td></tr> <tr><td>30h</td><td>-1.2</td><td>6Ch</td><td>-2.7</td></tr> <tr><td>34h</td><td>-1.3</td><td>70h</td><td>-2.8</td></tr> <tr><td>38h</td><td>-1.4</td><td>74h</td><td>-2.9</td></tr> <tr><td>3Ch</td><td>-1.5</td><td>78h</td><td>-3</td></tr> <tr><td>40h</td><td>-1.6</td><td>Other</td><td>NA</td></tr> </tbody> </table>	A[7:0]	VOCM	A[7:0]	VOCM	08h	-0.2	44h	-1.7	0Ch	-0.3	48h	-1.8	10h	-0.4	4Ch	-1.9	14h	-0.5	50h	-2	18h	-0.6	54h	-2.1	1Ch	-0.7	58h	-2.2	20h	-0.8	5Ch	-2.3	24h	-0.9	60h	-2.4	28h	-1	64h	-2.5	2Ch	-1.1	68h	-2.6	30h	-1.2	6Ch	-2.7	34h	-1.3	70h	-2.8	38h	-1.4	74h	-2.9	3Ch	-1.5	78h	-3	40h	-1.6	Other	NA
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0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																																																		
0	0	2D	0	0	1	0	1	1	0	1	<p>OTP Register Read for Display Option</p>	<p>Read Register for Display Option:</p> <p>A[7:0]: VCOM OTP Selection (Command 0x37, Byte A)</p> <p>B[7:0]: VCOM Register (Command 0x2C)</p> <p>C[7:0]~F[7:0]: Display Mode (Command 0x37, Byte B to Byte F) [5 bytes]</p> <p>G[7:0]~H[7:0]: Waveform Version (Command 0x37, Byte G to Byte J) [4 bytes]</p>																																																																
1	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																																																		
1	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀																																																																		
1	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀																																																																		
1	1		D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀																																																																		
1	1		E ₇	E ₆	E ₅	E ₄	E ₃	E ₂	E ₁	E ₀																																																																		
1	1		F ₇	F ₆	F ₅	F ₄	F ₃	F ₂	F ₁	F ₀																																																																		
1	1		G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G ₀																																																																		
1	1		H ₇	H ₆	H ₅	H ₄	H ₃	H ₂	H ₁	H ₀																																																																		
1	1		I ₇	I ₆	I ₅	I ₄	I ₃	I ₂	I ₁	I ₀																																																																		
1	1		J ₇	J ₆	J ₅	J ₄	J ₃	J ₂	J ₁	J ₀																																																																		
1	1		K ₇	K ₆	K ₅	K ₄	K ₃	K ₂	K ₁	K ₀																																																																		

0	0	2F	0	0	1	0	1	1	1	1	Status Bit Read	Read IC status Bit [POR 0x01] A[5]: HV Ready Detection flag [POR=0] 0: Ready 1: Not Ready A[4]: VCI Detection flag [POR=0] 0: Normal 1: VCI lower than the Detect level A[3]: [POR=0] A[2]: Busy flag [POR=0] 0: Normal 1: BUSY A[1:0]: Chip ID [POR=01] Remark: A[5] and A[4] status are not valid after RESET, they need to be initiated by command 0x14 and command 0x15 respectively.	
1	1		0	0	A ₅	A ₄	0	0	A ₁	A ₀			
0	0	32	0	0	1	1	0	0	1	0	Write LUT register	Write LUT register from MCU interface [100 bytes], which contains the content of VS [nX-LUT], TP #[nX], RP#[n]. Refer to Session Error! Reference source not found. Error! Reference source not found.	
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀			
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀			
0	1		:	:	:	:	:	:	:	:			
0	1		:	:	:	:	:	:	:	:			
0	0	3A	0	0	1	1	1	0	1	0	Set dummy line period	Set number of dummy line period Set A[6:0]=30h[POR] A[6:0]: Number of dummy line period in term of TGate Available setting 0 to 127.	
0	1		0	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀			
0	0	3B	0	0	1	1	1	0	1	1	Set Gate line width	Set Gate line width (TGate) A[3:0] = 1010 [POR] Remark: Default value will give 50Hz Frame frequency under 48 dummy line pulse setting.	
0	1		0	0	0	0	A ₃	A ₂	A ₁	A ₀			
0	0	3C	0	0	1	1	1	1	0	0	Border	Select border waveform for VBD	

0	1		A ₇	A ₆	A ₅	A ₄	0	0	A ₁	A ₀	Waveform Control	<p>A[7:0] = C0h [POR], set VBD as HiZ.</p> <p>A [7:6] :Select VBD option</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 10%;">A[7:6]</td> <td>Select VBD as</td> </tr> <tr> <td>00</td> <td>GS Transition, Defined in A[1:0]</td> </tr> <tr> <td>01</td> <td>Fix Level, Defined in A[5:4]</td> </tr> <tr> <td>10</td> <td>VOCM</td> </tr> <tr> <td>11[POR]</td> <td>HiZ</td> </tr> </table> <p>A [5:4] Fix Level Setting for VBD</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 10%;">A[5:4]</td> <td>VBD</td> </tr> <tr> <td>00[POR]</td> <td>VSS</td> </tr> <tr> <td>01</td> <td>VSH1</td> </tr> <tr> <td>10</td> <td>VSL</td> </tr> <tr> <td>11</td> <td>VSH2</td> </tr> </table> <p>A [1:0] GS Transition setting for VBD</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 10%;">A[1:0]</td> <td>VBD Transition</td> </tr> <tr> <td>00[POR]</td> <td>LUT0</td> </tr> <tr> <td>01</td> <td>LUT1</td> </tr> <tr> <td>10</td> <td>LUT2</td> </tr> <tr> <td>11</td> <td>LUT3</td> </tr> </table>	A[7:6]	Select VBD as	00	GS Transition, Defined in A[1:0]	01	Fix Level, Defined in A[5:4]	10	VOCM	11[POR]	HiZ	A[5:4]	VBD	00[POR]	VSS	01	VSH1	10	VSL	11	VSH2	A[1:0]	VBD Transition	00[POR]	LUT0	01	LUT1	10	LUT2	11	LUT3
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0	0	44	0	1	0	0	0	1	0	0	Set RAM X - address Start / End position	Specify the start/end positions of the window address in the X direction by an address unit for RAM																														
0	1		0	0	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																
0	1		0	0	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀																																
0	0	45	0	1	0	0	0	1	0	1	Set Ram Y-address Start / End position	Specify the start/end positions of the window address in the Y direction by an address unit for RAM																														
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																
0	1		0	0	0	0	0	0	0	A ₈																																
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀																																
0	1		0	0	0	0	0	0	0	B ₈		A[8:0]: YSA[8:0], Y Start, POR =000h B[8:0]: YEA[8:0], Y End, POR = 127h																														
0	0	4E	0	1	0	0	1	1	1	0	Set RAM X address counter	Make initial settings for the RAM X address in the address counter (AC) A[5:0]: 00h[POR].																														
0	1		0	0	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																
0	0	4F	0	1	0	0	1	1	1	1	Set RAM Y address counter	Make initial settings for the RAM Y address in the address counter (AC) A[8:0]: 000h [POR] .																														
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																
0	1		0	0	0	0	0	0	0	A ₈																																
0	0	74	0	1	1	1	0	1	0	0	Set Analog Block control	A[7:0] = 54h[POR]																														
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																
0	0	7E	0	1	1	1	1	1	1	0	Set Digital Block control	A[7:0] = 3Bh[POR]																														
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																
0	0	0C	0	0	0	0	1	1	0	0	Booster Soft	Booster Enable with Phase 1, Phase 2 and Phase 3																														

0	1		1	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	start Control for soft start current and duration setting. A[7:0] -> Soft start setting for Phase1 = 8Bh [POR] B[7:0] -> Soft start setting for Phase2 = 9Ch [POR] C[7:0] -> Soft start setting for Phase3 = 96h [POR] D[7:0] -> Duration setting = 0Fh [POR] Bit Description of each byte: A[6:0] / B[6:0] / C[6:0]:	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 20%;">Bit[6:4]</th> <th style="width: 80%;">Driving Strength Selection</th> </tr> </thead> <tbody> <tr><td>000</td><td>1(Weakest)</td></tr> <tr><td>001</td><td>2</td></tr> <tr><td>010</td><td>3</td></tr> <tr><td>011</td><td>4</td></tr> <tr><td>100</td><td>5</td></tr> <tr><td>101</td><td>6</td></tr> <tr><td>110</td><td>7</td></tr> <tr><td>111</td><td>8(Strongest)</td></tr> </tbody> </table> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 20%;">Bit[3:0]</th> <th style="width: 80%;">Min Off Time Setting of GDR [Time unit]</th> </tr> </thead> <tbody> <tr><td>0000</td><td rowspan="2" style="text-align: center;">NA</td></tr> <tr><td>~0011</td></tr> <tr><td>0100</td><td>2.6</td></tr> <tr><td>0101</td><td>3.2</td></tr> <tr><td>0110</td><td>3.9</td></tr> <tr><td>0111</td><td>4.6</td></tr> <tr><td>1000</td><td>5.4</td></tr> <tr><td>1001</td><td>6.3</td></tr> <tr><td>1010</td><td>7.3</td></tr> <tr><td>1011</td><td>8.4</td></tr> <tr><td>1100</td><td>9.8</td></tr> <tr><td>1101</td><td>11.5</td></tr> <tr><td>1110</td><td>13.8</td></tr> <tr><td>1111</td><td>16.5</td></tr> </tbody> </table> D[5:0]: duration setting of phase D[5:4]: duration setting of phase 3 D[3:2]: duration setting of phase 2 D[1:0]: duration setting of phase 1	Bit[6:4]	Driving Strength Selection	000	1(Weakest)	001	2	010	3	011	4	100	5	101	6	110	7	111	8(Strongest)	Bit[3:0]	Min Off Time Setting of GDR [Time unit]	0000	NA	~0011	0100	2.6	0101	3.2	0110	3.9	0111	4.6	1000	5.4	1001	6.3	1010	7.3	1011	8.4	1100	9.8	1101	11.5	1110	13.8	1111	16.5
Bit[6:4]	Driving Strength Selection																																																										
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0	1		1	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀																																																	
0	1		1	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀																																																	
0	1		0	0	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀																																																	
0	0	2B	0	0	1	0	1	0	1	1	Write Register for VCOM Control This command is used to reduce glitch when ACVCOM toggle. Two data bytes D04h and D63h should be set for this Command.																																																
0	1		0	0	0	0	0	1	0	0																																																	
0	1		0	1	1	0	0	0	1	1																																																	

8. Optical Specification

Measurements are made with that the illumination is under an angle of 45 degree, the detection is perpendicular unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ.	Max	Units	Notes
R	White Reflectivity	White	30	35	-	%	8-1
CR	Contrast Ratio	indoor	8:1		-		8-2
GN	2Grey Level	-	-	$DS+(WS-DS)*n(m-1)$			8-3
T update	Image update time	at 25 °C	-	3	-	sec	
Life		Topr		1000000times or 5years			

Notes: 8-1. Luminance meter: Eye-One Pro Spectrophotometer.

8-2. CR=Surface Reflectance with all white pixel/Surface Reflectance with all black pixels.

8-3 WS: White state, DS: Dark state

9. Handling, Safety, and Environment Requirements

Warning

The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

Caution

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components. Disassembling the display module.

Disassembling the display module can cause permanent damage and invalidates the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

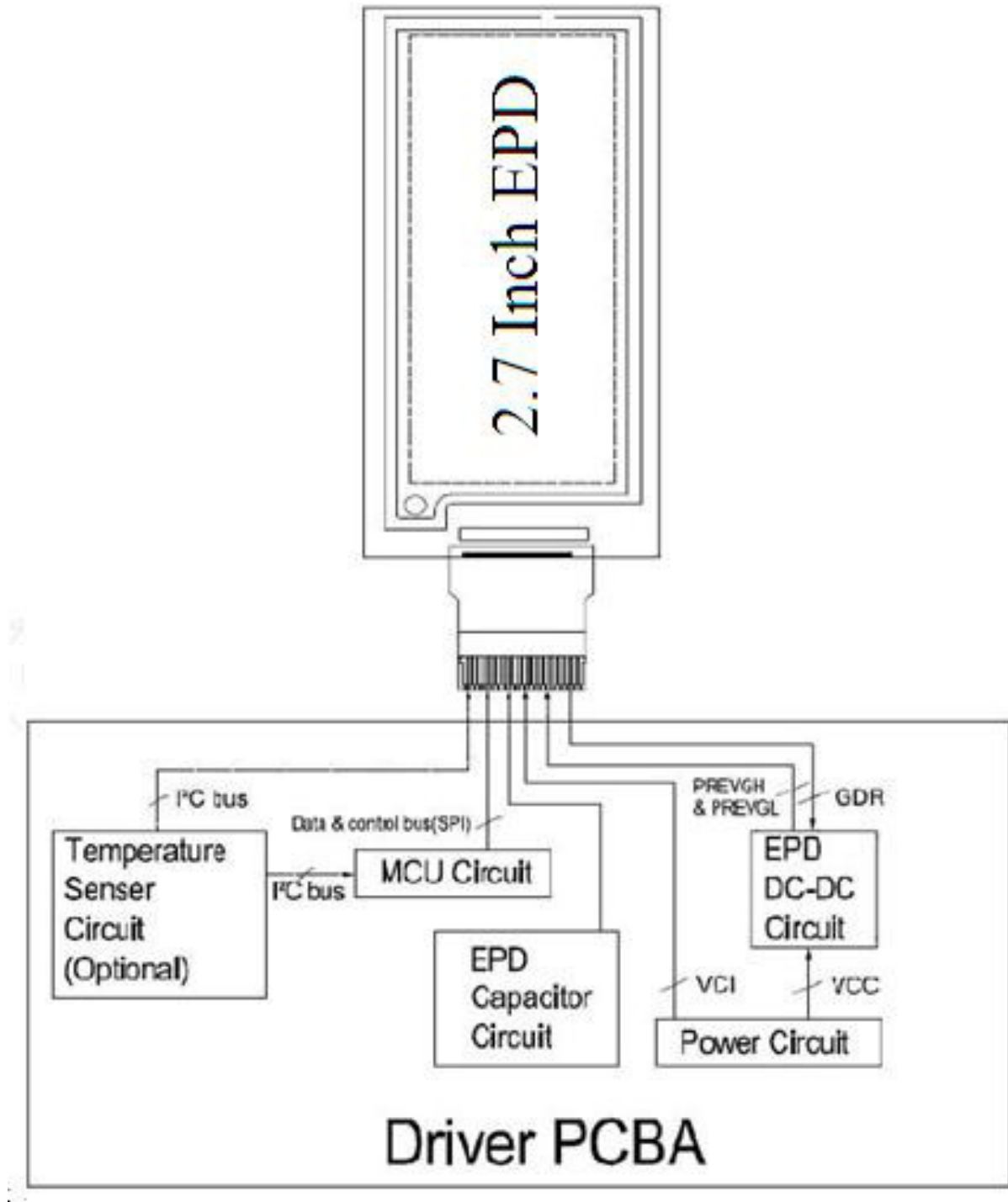
Data sheet status	
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

10. Reliability Test

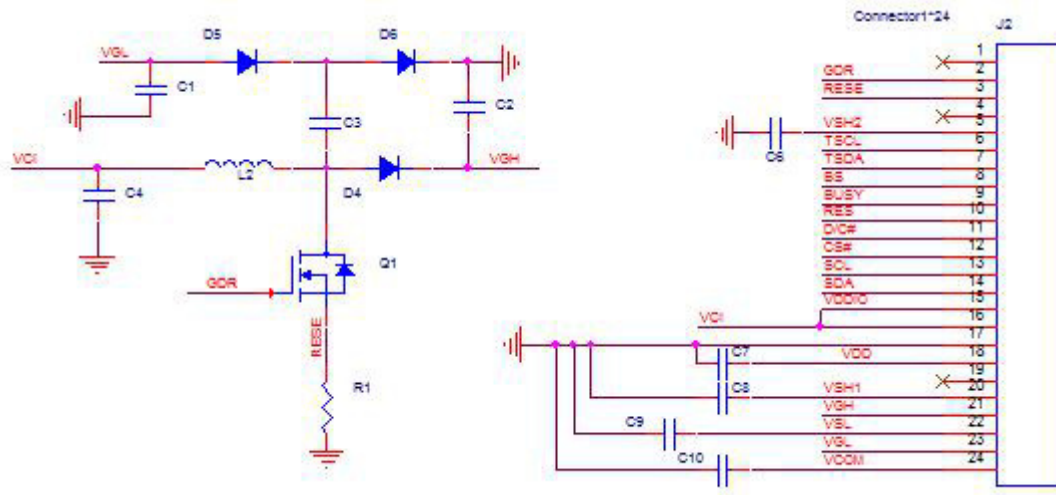
NO	Test items	Test condition
1	Low-Temperature Storage	T = -25°C, 240 h Test in white pattern
2	High-Temperature Storage	T = +70°C, RH=40% ,240h Test in white pattern
3	High-Temperature Operation	T = +50°C, RH = 30% ,240h
4	Low-Temperature Operation	0°C, 240h
5	High-Temperature, High-Humidity Operation	T=+40°C, RH=90%,240h
6	High Temperature, High Humidity Storage	T=+60°C, RH=80%,240h Test in white pattern
7	Temperature Cycle	1 cycle:[-25°C 30min]→[+70 °C 30 min] : 100 cycles Test in white pattern
8	UV exposure Resistance	765W/m ² for 168hrs,40 °C Test in white pattern
9	ESD Gun	Air+/-15KV;Contact+/-8KV (Test finished product shell,not display only) Air+/-8KV;Contact+/-6KV (Naked EPD display,no including IC and FPC area) Air+/-4KV;Contact+/-2KV (Naked EPD display,including IC and FPC area)

Note: Put in normal temperature for 1hour after test finished, display performance is ok.

11. Block Diagram



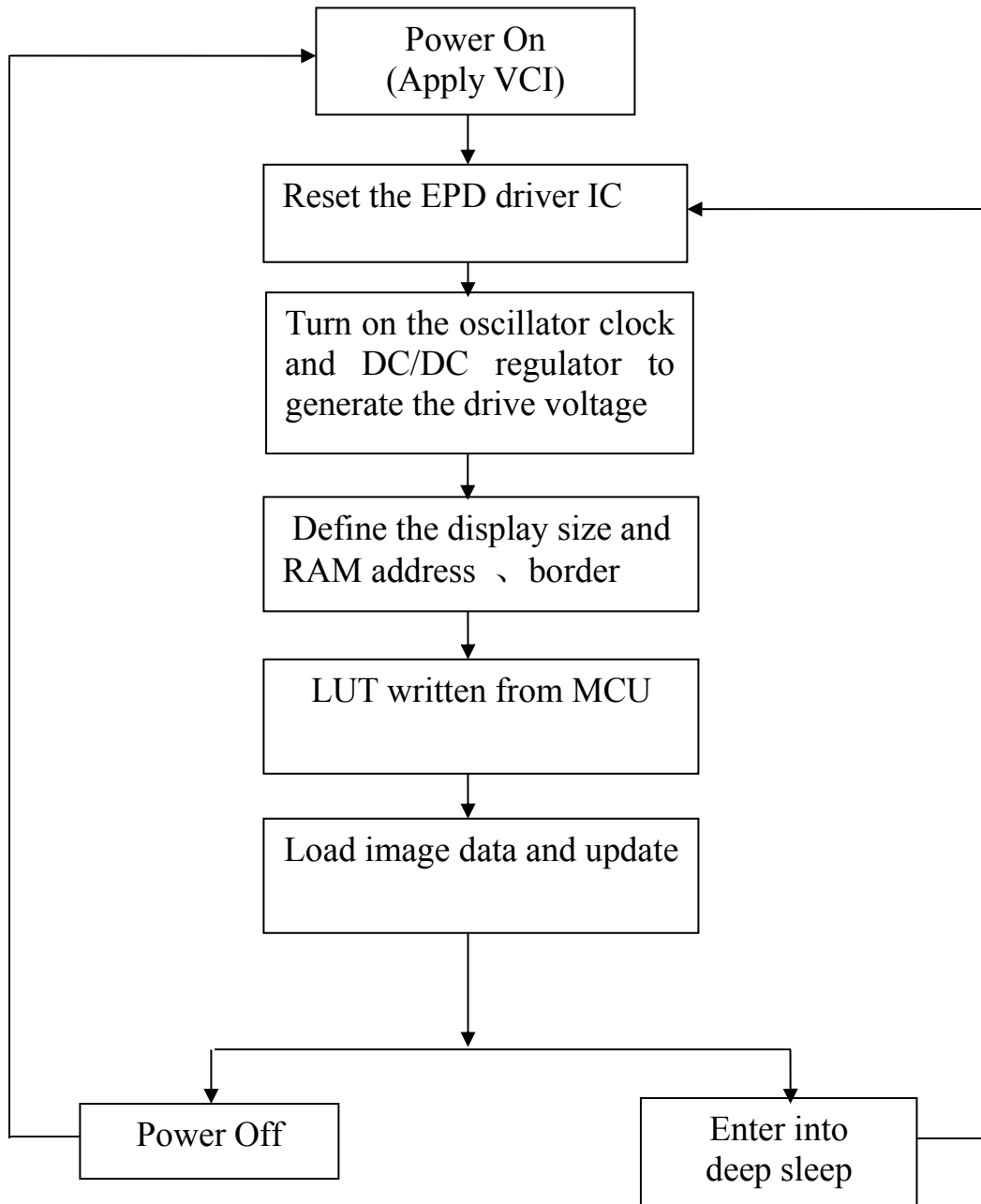
12. Typical Application Circuit with SPI Interface



Part Name	Value	Reference Part	Requirements for spare part
C4 C7	1uF	X5R/X7R; Voltage Rating: 6v or 25v	
C1 C2 C3 C6 C8 C9	1uF	0805; X5R/X7R; Voltage Rating: 25v 0603; 1) Samsung-CL10B105KA8NNNC 2) Taiyo-TMK107BJ105KA-T 3) TDK-C1608X7R1E105K7L Note: Effective capacitance > 0.35uF @ 18V DC bias	
C10	1uF	0805; X7R; Voltage Rating: 25v 0603; 1) Samsung-CL10B105KA8NNNC 2) Taiyo-TMK107BJ105KA-T 3) TDK-C1608X7R1E105K7L Note: Effective capacitance > 0.35uF @ 18V DC bias	
R1	2.2Ohm	0402, 0603, 0805; 1% variation, $\geq 0.05W$	
D4 D5 D6	Diode	MBR0530	1) Reverse DC Voltage $\geq 30V$ 2) $I_o \geq 500mA$ 3) Forward voltage $\leq 430mV$
Q1	NMOS	Si1304BDL/NX3008NBK	1) Drain-Source breakdown voltage $\geq 30V$ 2) $V_{gs(th)} = 0.9V(Typ), 1.3V(Max)$ 2) $R_{ds on} \leq 2.1 \Omega @ V_{gs} = 2.5V$
L2	47UH	CDRH2D18/LDNP-470NC	1) $I_o = 500mA(max)$

13 Typical Operating Sequence

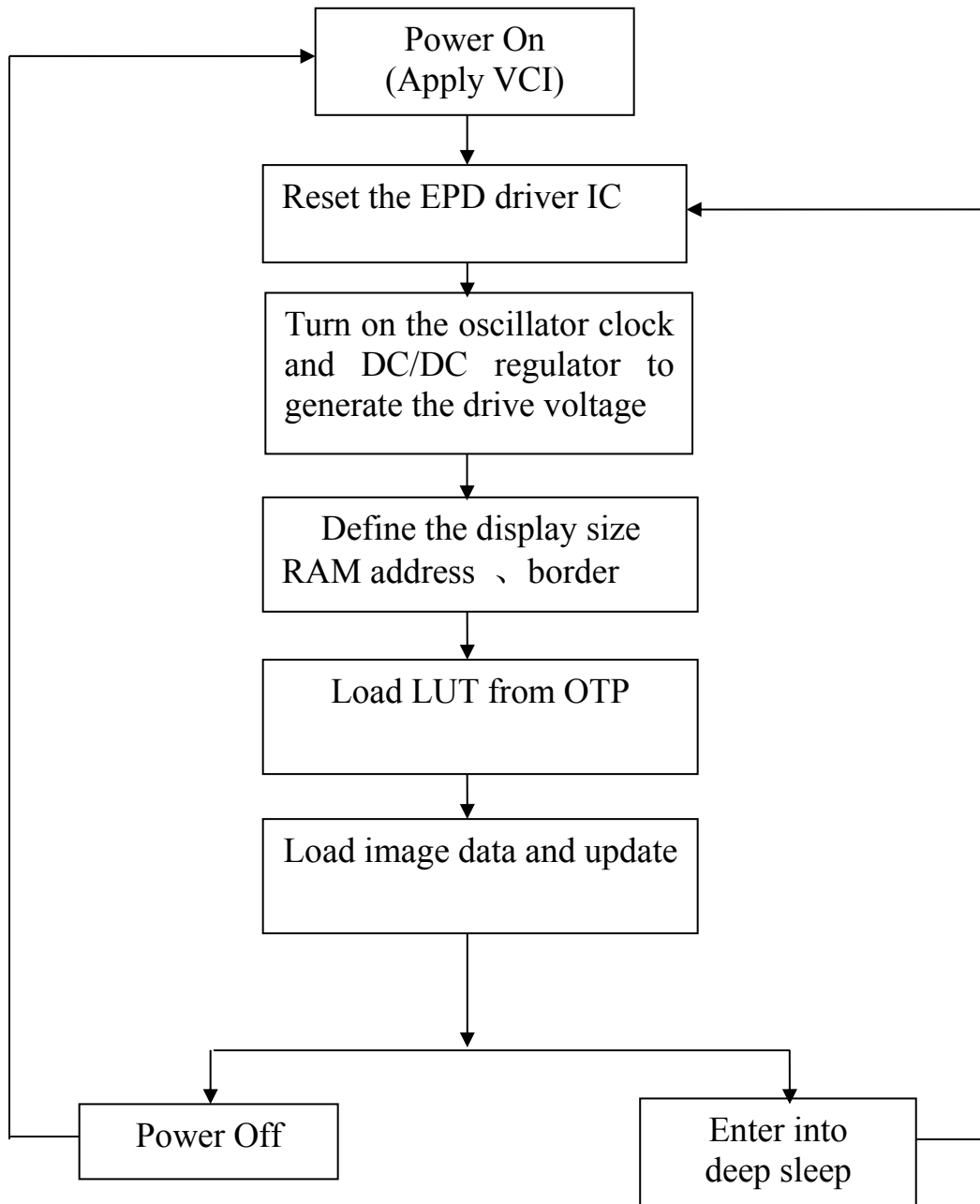
13.1 Normal Operation Flow



13.2 Normal Operation Reference Program Code

ACTION	VALUE/DATA	COMMENT
POWER ON		
delay	10ms	
PIN CONFIG		
RESE#	low	Hardware reset
delay	200us	
RESE#	high	
delay	200us	
Read busy pin		Wait for busy low
Command 0x12		Software reset
Read busy pin		Wait for busy low
Command 0x74	Data 0x54	Set Analog Block Control
Command 0x7E	Data 0x3B	Set Digital Block Control
Command 0x01	Data 0x97 0x00 0x00	Set display size and driver output control
Command 0x11	Data 0x01	Ram data entry mode
Command 0x44	Data 0x00 0x12	Set Ram X address
Command 0x45	Data 0x97 0x00 0x000x00	Set Ram Y address
Command 0x3C	Data 0x01	Set border
SET VOLTAGE AND LOAD LUT		
Command 0x2C	Data 0x52	Set VCOM value
Command 0x03	Data 0x17	Gate voltage setting
Command 0x04	Data 0x41 0x00 0x32	Source voltage setting
Command 0x3A	Data 0x11	Frame setting 50hz
Command 0x3B	Data 0x0D	
Command 0x32	Write 100bytes LUT	Load LUT
LOAD IMAGE AND UPDATE		
Command 0x4E	Data 0x00	Set Ram X address counter
Command 0x4F	Data 0x97 0x00	Set Ram Y address counter
Command 0x24	2888bytes	Load image (152/8*152)
Command 0x22	Data 0XC7	Image update
Command 0x20		
Read busy pin		Wait for busy low
Command 0x10	Data 0X01	Enter deep sleep mode
POWER OFF		

13.3 LUT from OTP Operation Flow



13.4 LUT from OTP Operation Reference Program Code

ACTION	VALUE/DATA	COMMENT
POWER ON		
delay	10ms	
PIN CONFIG		
RESE#	low	Hardware reset
delay	200us	
RESE#	high	
delay	200us	
Read busy pin		Wait for busy low
Command 0x12		Software reset
Read busy pin		Wait for busy low
Command 0x74	Data 0x54	Set Analog Block Control
Command 0x7E	Data 0x3B	Set Digital Block Control
Command 0x2B	Data 0x04 0x63	Write Register for VCOM Control
Command 0x0C	Data 0x8B 0x9C 0x96 0x0F	Set Booster Soft start
Command 0x01	Data 0x97 0x00 0x00	Set display size and driver output control
Command 0x11	Data 0x01	Ram data entry mode
Command 0x44	Data 0x00 0x12	Set Ram X address
Command 0x45	Data 0x97 0x00 0x00 0x00	Set Ram Y address
Command 0x3C	Data 0x01	Set border
LOAD LUT		
Command 0x18	Data 0x80	Set built-in temperature sensor
Command 0x22	Data 0xB1	Load LUT
Command 0x20		
Read busy pin		Wait for busy low
LOAD IMAGE AND UPDATE		
Command 0x4E	Data 0x00	Set Ram X address counter
Command 0x4F	Data 0x97 0x00	Set Ram Y address counter
Command 0x24	2888bytes	Load BW image (152/8*152)
Command 0x22	Data 0XC7	Image update
Command 0x20		
Read busy pin		Wait for busy low
Command 0x10	Data 0X01	Enter deep sleep mode
POWER OFF		

14. Part Number Definition

MT-DEP G 0270 B N S760 F0

1 2 3 4 5 6 7

1: MT-DEP:MT product

2: G:Dot matrix type

3: The E-paper size:2.7inch:0270

4: The color of E-paper:

B : Black/White R: Black/White/Red Y: Black/White/Yellow

5: OT range: N: Normal L/S: Low temperature H/W: High temperature

6: Driver type

7: FPC type

15. Inspection condition

15.1 Environment

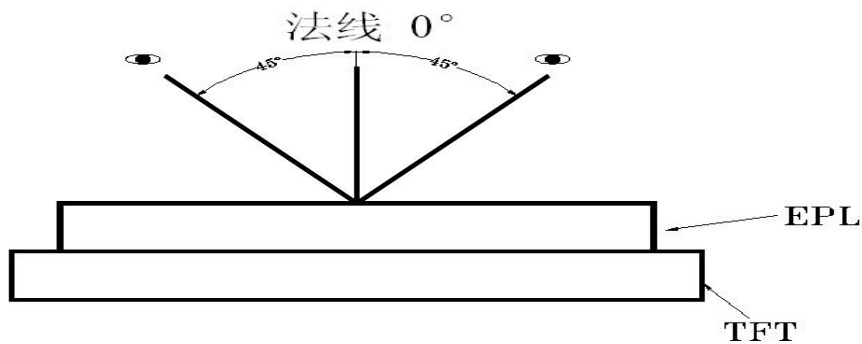
Temperature: $25\pm 3^{\circ}\text{C}$

Humidity: $55\pm 10\%\text{RH}$

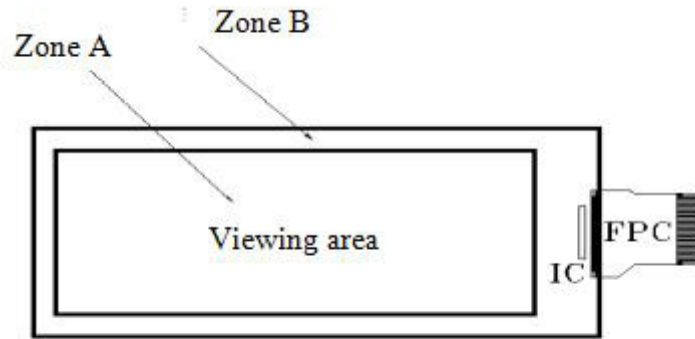
15.2 Illuminance

Brightness:1200~1500LUX;distance:20-30CM;Angle:Relate 45° surround.

15.3 Inspect method

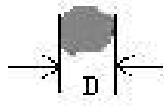
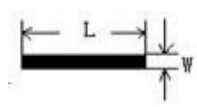


15.4 Display area



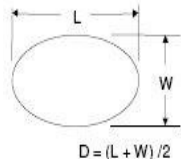
15.5 Inspection standard

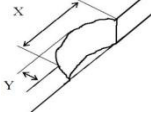
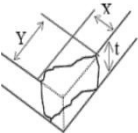
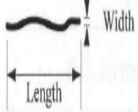



15.5.1 Electric inspection standard

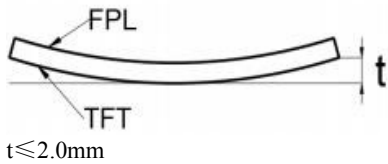
NO.	Item	Standard	Defect level	Method	Scope
1	Display	Display complete Display uniform	MA		
2	Black/White spots	 $D \leq 0.25\text{mm}$, Allowed $0.25\text{mm} < D \leq 0.4\text{mm}$, $N \leq 3$, and Distance $\geq 5\text{mm}$ $0.4\text{mm} < D$ Not Allow	MI	Visual inspection	Zone A
3	Black/White spots (No switch)	 $L \leq 0.6\text{mm}$, $W \leq 0.2\text{mm}$, $N \leq 1$ $L \leq 2.0\text{mm}$, $W > 0.2\text{mm}$, Not Allow $L > 0.6\text{mm}$, Not Allow		Visual/ Inspection card	
4	Ghost image	Allowed in switching process	MI	Visual inspection	

5	Flash spots/ Larger FPL size	Flash spots in switching, Allowed FPL size larger than viewing area, Allowed	MI	Visual/ Inspection card	Zone A Zone B
6	Display wrong/Missing	All appointed displays are showed correct	MA	Visual inspection	Zone A
7	Short circuit/ Circuit break/ Display abnormal	Not Allow			

15.5.2 Appearance inspection standard

NO.	Item	Standard	Defect level	Method	Scope
1	B/W spots /Bubble/ Foreign bodies/ Dents	 <p>$D = (L + W) / 2$ $D \leq 0.25\text{mm}$, Allowed $0.25\text{mm} < D \leq 0.4\text{mm}$, $N \leq 3$ $D > 0.4\text{mm}$, Not Allow</p>	MI	Visual inspection	Zone A
2	Glass crack	Not Allow	MA	Visual / Microscope	Zone A Zone B
3	Dirty	Allowed if can be removed	MI		Zone A Zone B

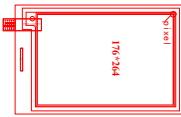
4	Chips/Scratch/ Edge crown	 <p>$X \leq 3\text{mm}, Y \leq 0.5\text{mm}$ And without affecting the electrode is permissible</p>  <p>$2\text{mm} \leq X$ or $2\text{mm} \leq Y$ Not Allow</p>  <p>$W \leq 0.1\text{mm}, L \leq 5\text{mm}$, No harm to the electrodes and $N \leq 2$ allow</p>	MI	Visual / Microscope	Zone A Zone B
5	TFT Cracks	 <p>Not Allow</p>	MA	Visual / Microscope	Zone A Zone B
6	Dirty/ foreign body	Allowed if can be removed/ allow	MI	Visual / Microscope	Zone A / Zone B
7	FPC broken/ Goldfingers oxidation/ scratch	  <p>Not Allow</p>	MA	Visual / Microscope	Zone B
8	TFT edge bulge /TFT chromatic aberration	<p>TFT edge bulge: $X \leq 3\text{mm}, Y \leq 0.3\text{mm}$ Allowed</p> <p>TFT chromatic aberration :Allowed</p>	MI	Visual / Microscope	Zone A Zone B
9	PCB damaged/ Poor welding/ Curl	<p>PCB (Circuit area) damaged Not Allow</p> <p>PCB Poor welding Not Allow</p> <p>PCB Curl $\leq 1\%$</p>			
10	Edge glue height/ Edge glue bubble	<p>Edge Adhesives $H \leq PS$ surface (Including protect film) Edge adhesives seep in $\leq 1/2$ Margin width</p> <p>Length excluding</p> <p>Edge adhesives bubble: bubble Width</p> <p>$\leq 1/2$ Margin width; Length $\leq 0.5\text{mm}$. $n \leq 5$</p>	MI	Visual / Ruler	Zone B

11	Protect film	Surface scratch but not effect protect function, Allowed		Visual Inspection	
12	Silicon glue	Thickness \leq PS surface(With protect film); Full cover the IC; Shape: The width on the FPC \leq 0.5mm (Front) The width on the FPC \leq 1.0mm (Back) smooth surface, No obvious raised.	MI	Visual Inspection	
13	Warp degree (TFT substrate)	 <p style="text-align: center;">$t \leq 2.0\text{mm}$</p>	MI	Ruler	
14	Color difference in COM area (Silver point area)	Allowed		Visual Inspection	

16.Packaging

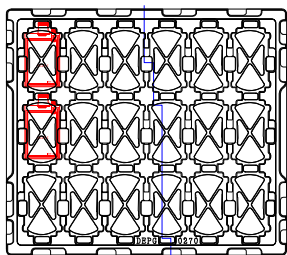
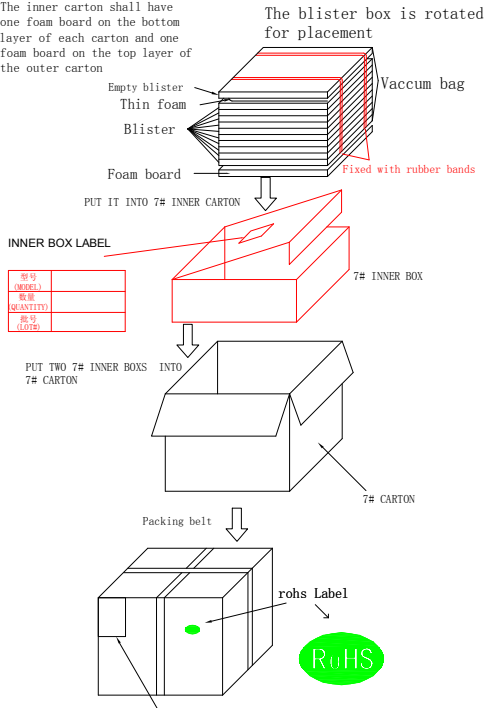
EPD PACKING INSTRUCTION						DATE
MT-DKE-QS. D-010						DESIGN
						CHECKED
						APPROVED

P/N	Customer Code	Ref. P/N	Type	PKG Method	Printing	Surface Marks	Pull Tape	Bar. Code
MT-DEPG0270RHS760F0			GLASS	Blister	BACK	None	YES	None

Marks instruction: print on the back of the product Contents: model+Lot#	Pull tape: 
--	--

Packing Materials List					18PCS/LAYER, 20LAYER/CTN, TOTAL 360PCS/CTN.
List	Model	Materials	Q'ty	Unit	Barcode Instruction:
Carton	7# 417*362*229 mm	corrugate	1	Piece	
BOX	7#(INNER) 400*343 *95 mm	corrugate	2	Piece	
Blister	MT-DEPG0270 PET1.0	PET	22	Piece	
Thin foam	319.4*259.02 T1.5-1.8MM	EPE	20	Piece	
Vaccum bag	450*590*0.075		2	Piece	
Foam board	MT-DKE2251-10	EPE	3	Piece	
PULL TAPE	16*5*T0.05		360	Piece	

Detail:

<p>Blister box:</p> <p>Note: there are 20 layers of products, divided into 2 inner boxes, and an empty blister box is placed on the top of each inner box, so the number of blister boxes is 22</p>  <p style="text-align: center;">QUANTITY: 18PCS</p>	<p>The inner carton shall have one foam board on the bottom layer of each carton and one foam board on the top layer of the outer carton</p> <p>The blister box is rotated for placement</p>  <p>Shipping marks according to customer's requirements</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th colspan="2">Epaper Identification</th> </tr> </thead> <tbody> <tr> <td>QC:</td> <td>PASS</td> </tr> <tr> <td>Model No.</td> <td>_____</td> </tr> <tr> <td>Quantity</td> <td>_____ pcs</td> </tr> <tr> <td>Date:</td> <td>_____</td> </tr> <tr> <td>Carton No.</td> <td>_____ of _____</td> </tr> </tbody> </table>	Epaper Identification		QC:	PASS	Model No.	_____	Quantity	_____ pcs	Date:	_____	Carton No.	_____ of _____
Epaper Identification													
QC:	PASS												
Model No.	_____												
Quantity	_____ pcs												
Date:	_____												
Carton No.	_____ of _____												

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[E2969CS0B1](#)